



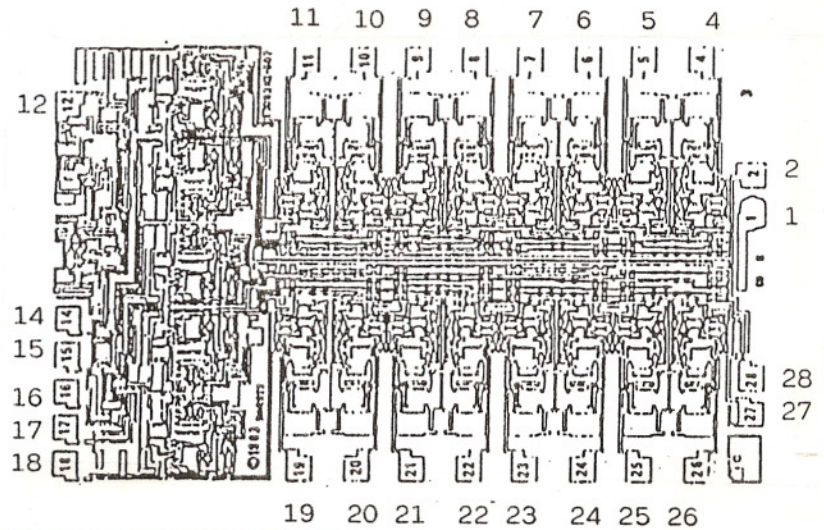
Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

<u>PAD NO</u>	<u>FUNCTIONS</u>
1	+V Supply
2	Out B
3	NC
4	In 8B
5	In 7B
6	In 6B
7	In 5B
8	In 4B
9	In 3B
10	In 2B
11	In 1B
12	GND
13	NC
14	NC
15	Address A2
16	Address A1
17	Address A0
18	Enable
19	In 1A
20	In 2A
21	In 3A
22	In 4A
23	In 5A
24	In 6A
25	In 7A
26	In 8A
27	-V Supply
28	Out A



NOTE: SUBSTRATE MAY BE CONNECTED TO -V SUPPLY
OR MAY BE LEFT FLOATING

Topside Metal: Al
Backside: Au
Backside Potential: Ground
Mask Ref:
Bond Pads : .004" min

APPROVED BY: CD

MFG: Harris

DIE SIZE : .129" x .082"

THICKNESS: .020"

DATE: 2/5/01

P/N: HIO-507